



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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版数 REV.	年月日 DATE	図番 DRAWING NO.	変更内容 DESCRIPTION	製図 DR.	担当 CHK.	承認 APPD.	承認 APPD.
2	19.May.2009	066789	CHANGED FORM ETC.		Y.ITOU		Y.MIZUSAWA
3	29.Oct.2009	068879	DELETE UL NOTATION.		Y.ITOU		Y.MIZUSAWA

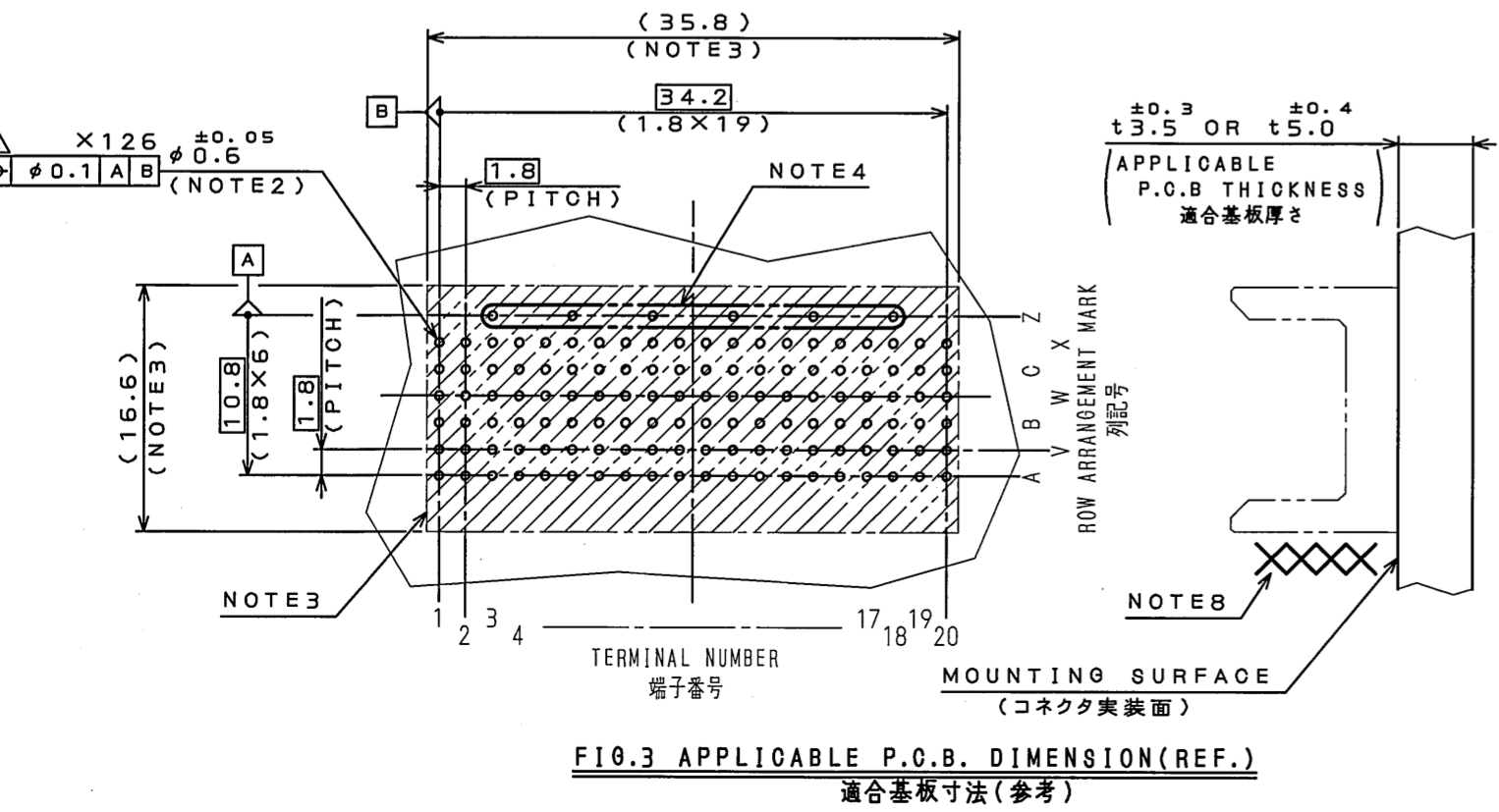
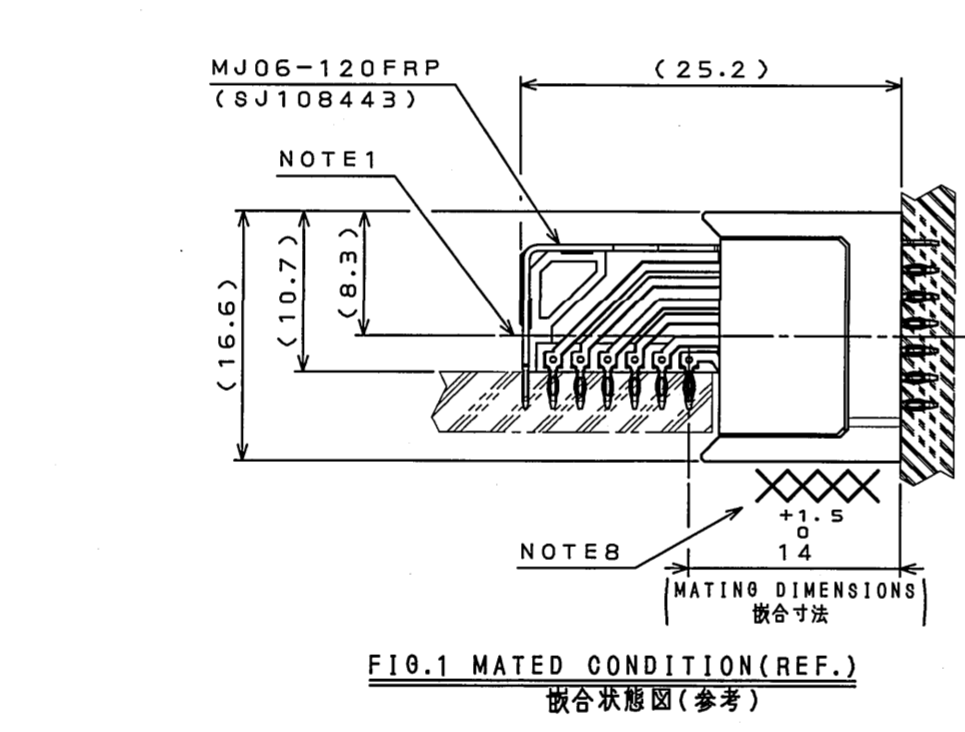
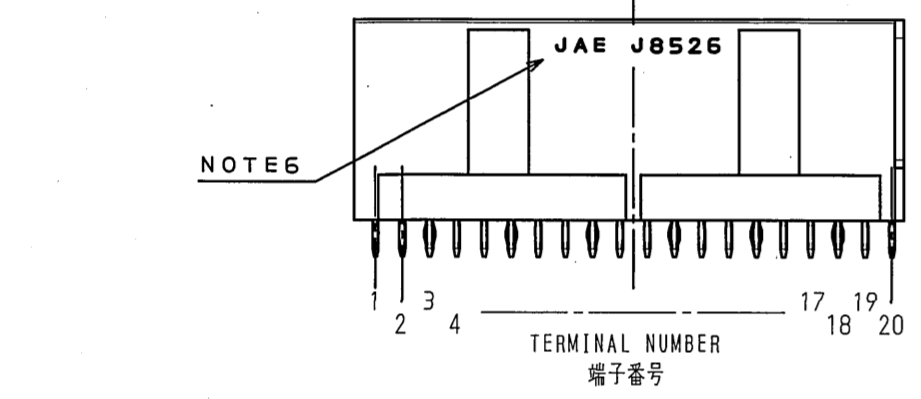
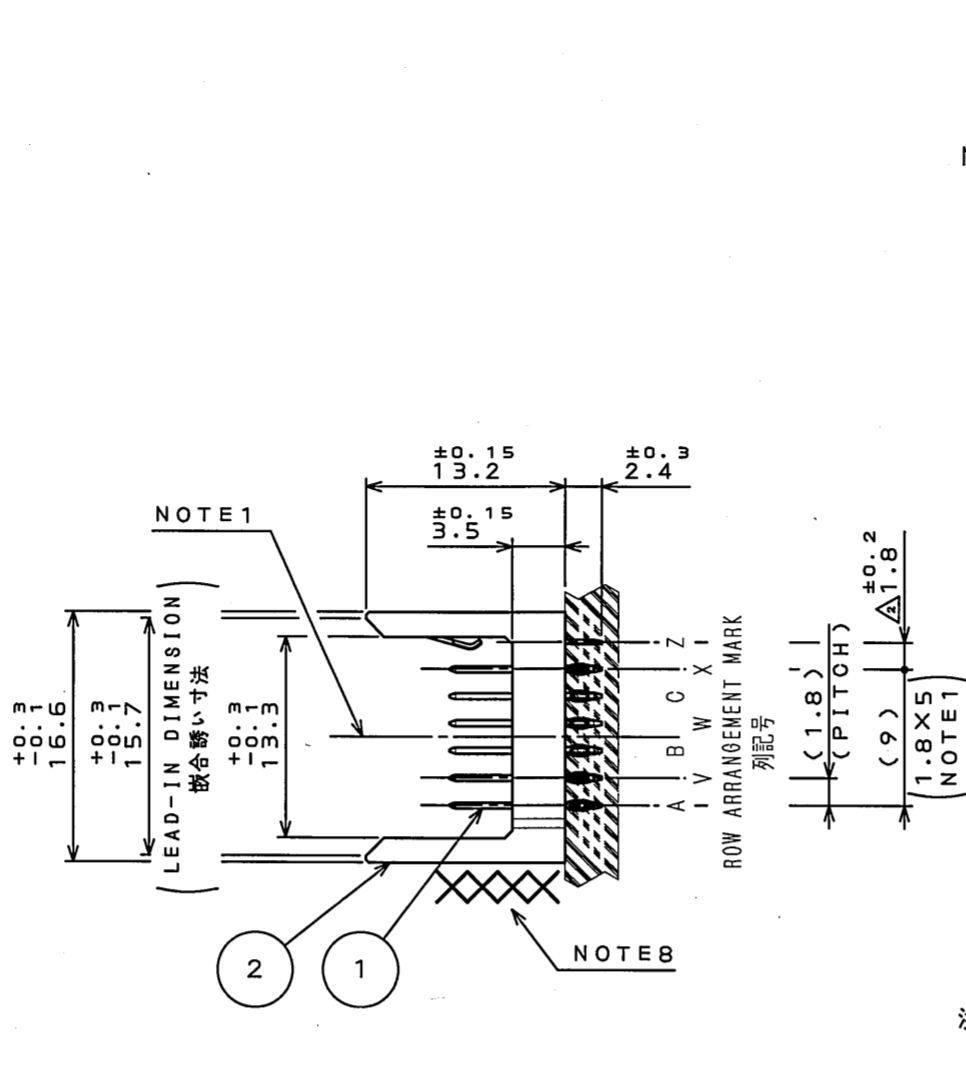
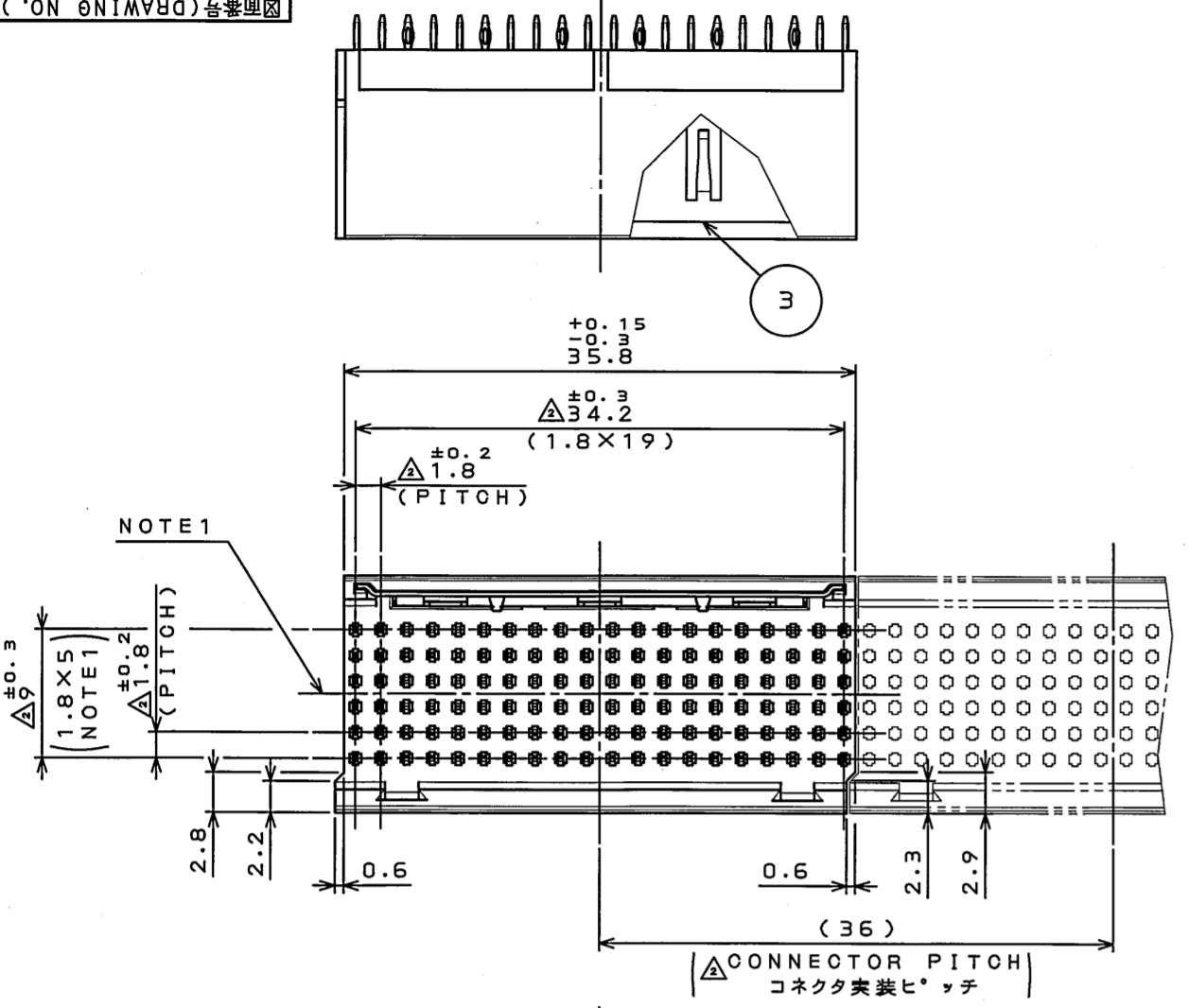
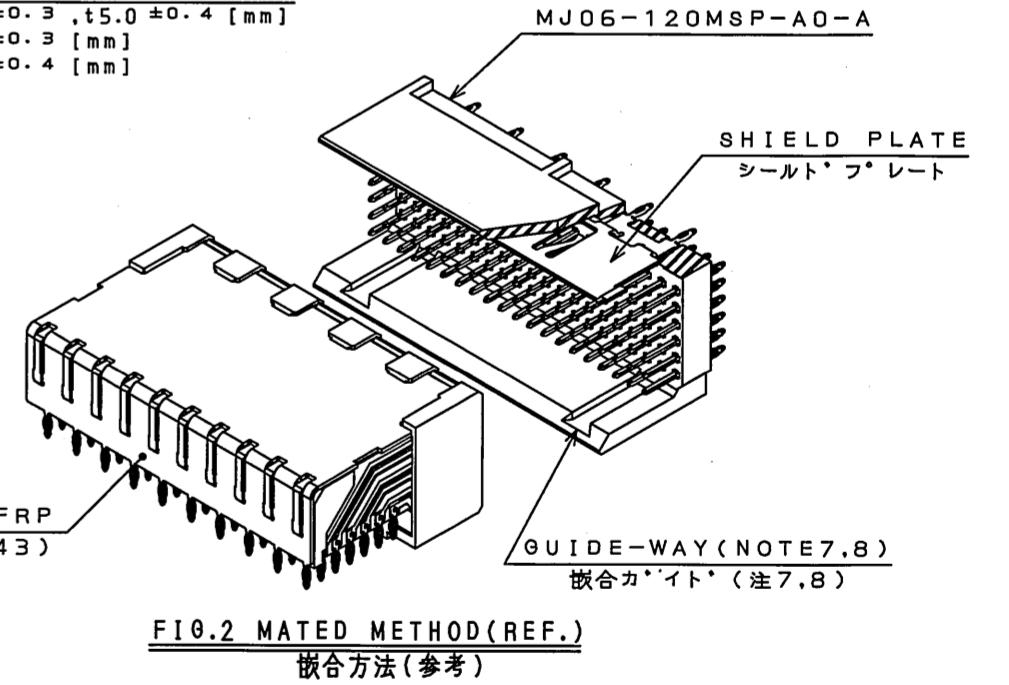


TABLE1 P.C.B. THROUGH-HOLE SIZE (REF.)
基板スルーホール寸法 (参考)

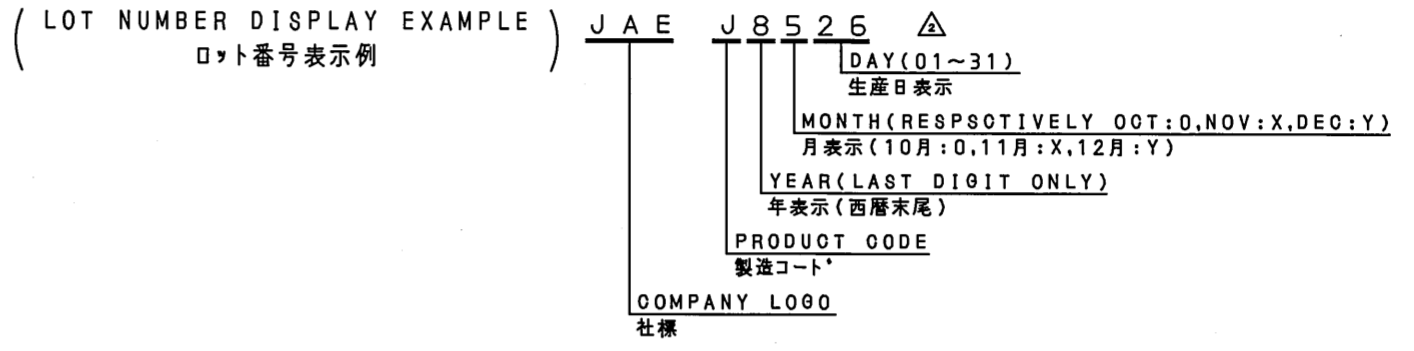
FINISHED HOLE DIAMETER (GOLD OVER COPPER PLATING) 仕上がり径 (銅上Auフラッシュめっき)	±0.05 φ0.6 [mm]
STARTED DRILL DIAMETER ドリル下穴径	±0.025 φ0.7 [mm]
COPPER PLATING THICKNESS 銅めっき厚	20 [μm] MIN.
P.C.B. MATERIAL 基板材料	GLASS FILLED EPOXY ガラス布入りエポキシ積層板

MJ06-120MSP-A0-A
PRODUCT IDENTIFICATION MARK 製品識別記号

APPLICABLE P.C.B THICKNESS 適合基板厚さ	適合基板厚さ
0: FOR t3.5±0.3 AND t5.0±0.4 [mm]	0: t3.5±0.3, t5.0±0.4 [mm]
3: FOR t3.5±0.3 [mm] ONLY	3: t3.5±0.3 [mm]
5: FOR t5.0±0.4 [mm] ONLY	5: t5.0±0.4 [mm]
INSULATOR STYLE インシュレータ形状	インシュレータ形状
A: FOR ANGLE-SOCKET	A: 対アングルソケット
H: FOR HARNESS-SOCKET	H: 対ハーネスソケット
TERMINATION STYLE 結線方式	結線方式
P: PRESS-FIT	P: フレスフィット
H: HARNESS	H: ハーネス
CONNECTING DIRECTION 接続方向	接続方向
R: RIGHT-ANGLE	R: ライトアングル
S: STRAIGHT	S: ストレート
PRODUCT STYLE 製品形態	製品形態
F: SOCKET-CONTACT	F: ソケットコンタクト
M: PIN-CONTACT	M: ピンコンタクト
S: SHROUD	S: ショウド
C: HARNESS-CLIP	C: ハーネスクリップ
NUMBER OF CONTACTS 芯数	芯数
12	12



- NOTE1. THIS LINE IS A CENTERLINE OF TOTAL-PITCH: 9 (1.8X5).
 2. TABLE1 SHOWS P.C.B. THROUGH-HOLE SIZE.
 3. [Hatched Area]: CONNECTOR MOUNTING AREA (FIG.3 REF.).
 4. [Dashed Line]: THE 6 THROUGH-HOLES IN Z-ROW IS SHORT-CIRCUITED (FIG.3 REF.).
 5. PLATING THICKNESS
 CONTACT AREA : GOLD (0.1μm MIN.) OVER NICKEL (1.5~5.0μm) PLATING.
 PRESS-FIT AREA : GOLD (0.03μm MIN.) OVER NICKEL (1.5~5.0μm) PLATING.
 6. COMPANY LOGO "JAE" AND PRODUCTION LOT NUMBER AS INDICATED.



7. NOTE IT IN DIRECTION OF THE CONNECTOR (FIG.2 REF.).
 8. [X-Mark]: THE GUIDE-WAY SIDE
- 注1. 寸法9 (1.8x5)の中心線を示す。
 2. スルーホール仕様をTABLE1に示す。
 3. [Hatched Area]はコネクタ実装領域を示す (FIG.3 参照)。
 4. [Dashed Line]内のZ列のスルーホールは、コネクタ構造上同一端子である (FIG.3 参照)。
 5. めっき仕様
 接触部: ニッケル (1.5~5.0μm)上 金めっき (0.1μm以上)
 結線部: ニッケル (1.5~5.0μm)上 金フラッシュめっき (0.03μm以上)
 6. 図示の位置に社標、ロット番号を表示する。
 7. 図示のガイドに沿って、嵌合すること (FIG.2 参照)。
 8. [X-Mark]は、嵌合ガイド側を示す。

3 SHIELD-PLATE	1 COPPER ALLOY	NOTES	
2 INSULATOR	1 GLASS FILLED PBT		COLOR: WHITE Δ
1 CONTACT	120 COPPER ALLOY	NOTES	
符号 NO.	名称 DESCRIPTION	個数 QTY.	材料 MATERIAL
仕様書 (SPECIFICATION)	JACS-10524	第1版 (ORIGINAL DATE)	26.May.2008
公差 (GENERAL TOLERANCE)		製図 DR.	
寸法 (DIMENSION)		担当 CHK.	Y.ITOU
		承認 APPD.	
		承認 APPD.	Y.MIZUSAWA
		尺貫 (SCALE)	2:1
		シリーズ (SERIES)	MJ06
		名称 (TITLE)	MJ06-120MSP-A0-A PIN-HEADER SHORT (FOR ANGLE-SOCKET)
		質量 (MASS)	6.7 [g]
		図面番号 (DRAWING NO.)	SJ108444
		備考 REMARKS	日本航空電子工業株式会社 JAE ELECTRONICS INDUSTRY, LTD.